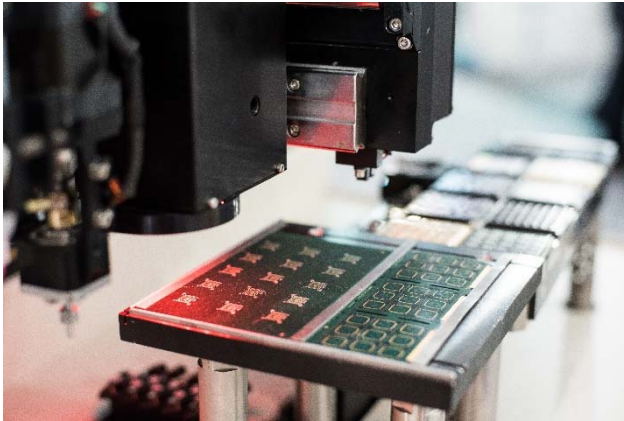


# Model 6200 Semi-Automatic High Accuracy Die Attach System





**Double Dispenser** for two different adhesives.

**Stamping (Pin Transfer)** 75 µm adhesive dots.

**Die Presentation:**

- Up to 10 Waffle/Gel packs 2"
- Up to 8 Tape & Reel feeders
- Bulk and other feeders
- Combinations of the above

Unique one-pass, wet **Die Stacking** capability with **BLT control** of the dice.

Handles **MEMS, Sensors, Imaging Devices**, etc.

Multi-chip **Ag Sintering** using paste or Ag sheet.

**Flip Chip, C2/C4** process including chip flipping, bump fluxing and final alignment over a high resolution Up Looking Camera.

**Gold Bump Flip Chip** based on Ultrasonic, Thermo-compression, ACF/ACP, **Eutectic MCM** high temperature up to 500°C processes based on heated substrates and heated pickup tools, with provision of forming gas.

Performs **MCM, Flip Chip, Eutectic, Silver Glass, Ag Sintering** etc die attach applications.

**Small** footprint, **Table-Top** configuration. **Versatile** and **user friendly** machine using the same advanced software of Model 6400 running under Windows® on a PC platform.

**Semi-automatic and Fully automatic** process allowing highest flexibility and easy operation.

**Very High Accuracy** servo systems control the main axes.

High resolution **Digital Vision** and advanced **Image Processing** system.

**Time-Pressure, Volumetric or Jet Dispenser** for applying thermal or UV curing adhesives.

Specification Highlights	
Work Area	Up to 6" x 6".
Die size range	0.006" to over 2"
Die Material	GaAs, Si, Glass, etc.
Substrates	Lead Frames, Ceramic, Silicon Wafers, PCB's, Metal, TO cans, etc.
Pickup/Bond Force	40 to 9,000 grams.
Placement Accuracy	Better than +/-3 µm @ - application dependent.
Throughput	Up to 700 CPH – application dependent.
Size	0.97 x 0.85 x 0.65 m
Weight	About 200 kg